

What is claimed is:

1. A substrate processing apparatus comprising:

a processing part configured to process a substrate;

a transporting part configured to transport a substrate before processing to the processing part; and

a cleaning part configured to clean a processed substrate, wherein

the cleaning part has a first cleaning unit and a second cleaning unit that are vertically arranged in two stages;

the first cleaning unit and the second cleaning unit each have a plurality of cleaning modules that are arranged in series; and

the transporting part has

a cover extending in an arrangement direction of the plurality of cleaning modules and formed with a carry-in port at one end thereof,

a slide stage disposed inside the cover and configured to transport a substrate before processing along the arrangement direction of the plurality of cleaning modules, and

an exhaust duct provided at the opposite side to the carry-in port of the cover and configured to evacuate inside the cover.

2. A substrate processing apparatus comprising:

a polishing part configured to polish a substrate;

a transporting part configured to transport a substrate before polishing to the polishing part; and

a cleaning part configured to clean a polished substrate,
wherein

the cleaning part has

a plurality of cleaning modules arranged in series, and
a cleaning-part transport mechanism configured to
transport a substrate between the cleaning modules each; and

the cleaning-part transport mechanism has

two sets each consisting of

a pair of arms that are openable/closable and
configured to hold a substrate,

a vertical-moving mechanism configured to
vertically move the pair of arms, and

a rotating mechanism configured to rotate the pair
of arms around a rotating shaft that is in parallel with an
opening/closing direction, and

an arm-transport mechanism configured to linearly move
the two sets along an arrangement direction of the plurality
of cleaning modules.

3. The substrate processing apparatus according to claim 2
further comprising a control part configured to control an
operation of the cleaning part, wherein

the control part controls an operation of the cleaning
part such that, when the rotating mechanism rotates the pair
of arms so as to direct tips of the pair of arms upward, the
vertical-moving mechanism lowers the pair of arms.

4. The substrate processing apparatus according to claim 2, wherein

the pair of arms are provided with chuck tops capable of abutting to an outer periphery of a substrate, vertically arranged in multiple stages.

5. The substrate processing apparatus according to claim 2, wherein

a set consisting of the pair of arms, the vertical-moving mechanism, and the rotating mechanism is disposed in a suspended state below the arm-transport mechanism.

6. The substrate processing apparatus according to claim 2, wherein

the cleaning part further has a pre-cleaning module arranged on a same line as the plurality of cleaning modules and configured to clean a substrate before polishing; and

the cleaning-part transport mechanism transports a substrate between the pre-cleaning module and each of the cleaning modules.